



INA300-Q1 汽车级过流保护、电流感测比较器

1 特性

- 适用于汽车电子 应用
- 具有符合 AEC-Q100 标准的下列结果：
 - 器件温度 1 级：-40°C 至 +125°C 的环境运行温度范围
 - 器件人体放电模式 (HBM) 静电放电 (ESD) 分类等级 2
 - 器件组件充电模式 (CDM) ESD 分类等级 C6
- 宽共模范围：0V 至 36V
- 可选响应时间：
 - 10μs, 50μs, 100μs
- 可编程阈值：
 - 使用单个电阻调节
 - 可编程范围为 0mV 到 250mV
- 精度：
 - 偏移电压：±500μV (最大值)
 - 偏移电压漂移：0.5μV/°C (最大值)
- 可选滞后：
 - 2mV, 4mV, 8mV
- 有效静态电流：135μA (最大值)
- 可选禁用模式
 - 禁用模式下的静态电流：3.5μA (最大值)
 - 禁用模式下的输入偏置电流：500nA (最大值)
- 锁存模式下的开漏输出

2 应用

- 车身控制模块
- 电机控制
- 阀门控制
- 中央控制模块

3 说明

INA300-Q1 是一款高共模电流感测比较器。该比较器通过测量电流感测电阻或分流电阻两端产生的电压检测过流情况。此器件能够在 0V 至 36V 的共模电压范围内测量该差分电压信号，与电源电压无关。INA300-Q1 器件 特有一个可调节阈值范围。该范围由单个外部限值设定电阻设置。可选滞后特性可调节比较器的运行状态，以适应 0mV 至 250mV 的宽输入信号范围。

器件上的开漏报警输出可配置为透明模式（输出状态与输入状态保持一致）或锁存模式（清零锁存时清除报警输出）。器件响应时间设置是可选的，10μs 内即可迅速发出过流报警。

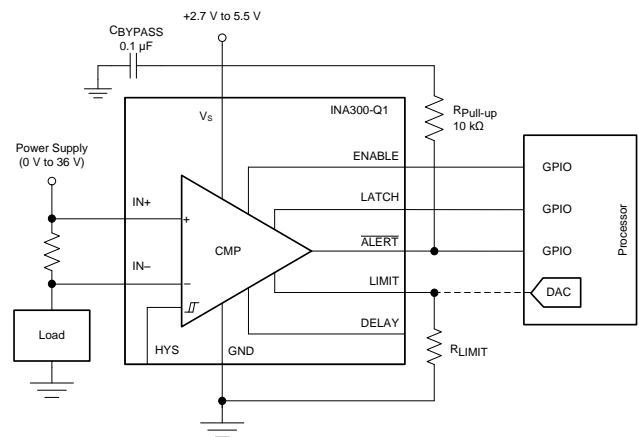
INA300-Q1 器件由 2.7V-5.5V 单电源供电运行，最大电源电流消耗为 135μA。INA300-Q1 器件的额定扩展工作温度范围为 -40°C 至 +125°C，采用超薄小外形尺寸封装 (VSSOP)-10 封装。

器件信息⁽¹⁾

器件型号	封装	封装尺寸 (标称值)
INA300-Q1	VSSOP (10)	3.00mm × 3.00mm

(1) 要了解所有可用封装，请参见数据表末尾的封装选项附录。

典型应用电路原理图



Copyright © 2016, Texas Instruments Incorporated



目录

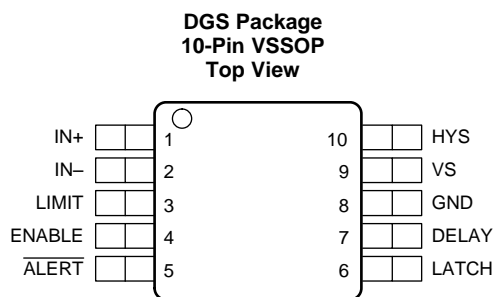
1	特性	1	7.4	Device Functional Modes	18
2	应用	1	8	Applications and Implementation	23
3	说明	1	8.1	Application Information	23
4	修订历史记录	2	8.2	Typical Applications	23
5	Pin Configuration and Functions	3	9	Power Supply Recommendations	29
6	Specifications	4	10	Layout	29
6.1	Absolute Maximum Ratings	4	10.1	Layout Guidelines	29
6.2	ESD Ratings	4	10.2	Layout Example	30
6.3	Recommended Operating Conditions	4	11	器件和文档支持	31
6.4	Thermal Information	4	11.1	文档支持	31
6.5	Electrical Characteristics	5	11.2	接收文档更新通知	31
6.6	Timing Requirements	5	11.3	社区资源	31
6.7	Typical Characteristics	6	11.4	商标	31
7	Detailed Description	10	11.5	静电放电警告	31
7.1	Overview	10	11.6	Glossary	31
7.2	Functional Block Diagram	10	12	机械、封装和可订购信息	31
7.3	Feature Description	11			

4 修订历史记录

注：之前版本的页码可能与当前版本有所不同。

Changes from Original (December 2015) to Revision A	Page
• 已将产品状态由“产品预览”更改为“量产数据”	1
• 已更改数据表标题	1

5 Pin Configuration and Functions



Pin Functions

PIN		I/O	DESCRIPTION
NO.	NAME		
1	IN+	Analog input	Connect to supply side of shunt resistor.
2	IN–	Analog input	Connect to load side of shunt resistor.
3	LIMIT	Analog input	Alert threshold limit input. See Setting The Current-Limit Threshold for details on setting limit threshold.
4	ENABLE	Digital input	Enable or disable selection input
5	ALERT	Digital output	Overlimit alert, active-low, open-drain output.
6	LATCH	Digital input	Transparent or latch mode selection input.
7	DELAY	Digital input	Response time selection input.
8	GND	Analog	Ground
9	VS	Analog	Power supply, 2.7 V to 5.5 V.
10	HYS	Digital input	Hysteresis setting input. See Selectable Hysteresis for hysteresis settings.

6 Specifications

6.1 Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
Supply voltage, V_S			6	V
Analog inputs (IN+, IN–)	Differential ($V_{IN+} - V_{IN-}$) ⁽²⁾	–40	40	V
	Common-mode ⁽³⁾	GND – 0.3	40	
Analog input	LIMIT	GND – 0.3	$(V_S) + 0.3$	V
Digital inputs	LATCH, DELAY, ENABLE, HYS	GND – 0.3	$(V_S) + 0.3$	V
Alert output		GND – 0.3	6	V
Operating temperature		–40	125	°C
Junction temperature, T_J			150	°C
Storage temperature, T_{stg}		–65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) V_{IN+} and V_{IN-} are the voltages at the IN+ and IN– terminals, respectively.

(3) Input voltage may exceed the voltage shown if the current at that terminal is limited to 5 mA.

6.2 ESD Ratings

		VALUE	UNIT
$V_{(ESD)}$ Electrostatic discharge	Human-body model (HBM), per AEC Q100-002 ⁽¹⁾	±2500	V
	Charged-device model (CDM), per AEC Q100-011	±1000	

(1) AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
V_{CM}	Common-mode input voltage		12		V
V_S	Operating supply voltage	2.7	3.3	5.5	V
	Delay setting		100		µs
T_A	Operating free-air temperature	–40		125	°C

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		INA300-Q1	UNIT
		DGS (VSSOP)	
		10 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	169.4	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	59.1	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	89.6	°C/W
ψ_{JT}	Junction-to-top characterization parameter	8.5	°C/W
ψ_{JB}	Junction-to-board characterization parameter	88.3	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see [Semiconductor and IC Package Thermal Metrics](#).

6.5 Electrical Characteristics

at $T_A = 25^\circ\text{C}$, $V_{\text{SENSE}} = V_{\text{IN}+} - V_{\text{IN}-} = 0\text{ mV}$, $V_S = 3.3\text{ V}$, $V_{\text{IN}+} = 12\text{ V}$, $V_{\text{LIMIT}} = 10\text{ mV}$, and $\text{DELAY} = 100\text{ }\mu\text{s}$ (unless otherwise noted)

PARAMETER		CONDITIONS	MIN	TYP	MAX	UNIT
INPUT						
V _{CM}	Common-mode input voltage		0		36	V
V _{IN}	Differential input voltage	V _{IN} = V _{IN+} – V _{IN–}	0		250	mV
CMR	Common-mode rejection	V _{IN+} = 0 V to 36 V, T _A = –40°C to 125°C	100	120		dB
V _{OS}	Offset voltage, RTI ⁽¹⁾	V _S = 3.3 V, DELAY = 100 μs		–75	–500	μV
		V _S = +3.3 V, DELAY = 50 μs		–125	–500	
		V _S = +3.3 V, DELAY = 10 μs ⁽²⁾		–350	–650	
dV _{OS} /dT	Offset voltage drift, RTI ⁽¹⁾	T _A = –40°C to 125°C		0.1	0.5	μV/°C
PSR	Power-supply rejection ratio	V _S = 2.7 V to 5.5 V, V _{IN+} = 12 V, T _A = –40°C to 125°C		75	150	μV/V
I _B	Input bias current			5	10	μA
		Disable mode		0.05	0.5	
I _{OS}	Input offset current			±0.1		μA
I _{LIMIT}	Limit threshold output current	T _A = 25°C	19.9	20	20.1	μA
		T _A = –40°C to 125°C	19.85		20.15	
DIGITAL INPUT/OUTPUT						
t _p	Alert propagation delay	Delay = open, overdrive = 1 mV		10		μs
		Delay = GND, overdrive = 1 mV		50		
		Delay = V _S , overdrive = 1 mV		100		
HYS	Hysteresis	HYS = open		2		mV
		HYS = GND		4		
		HYS = V _S		8		
V _{IH}	High-level input voltage	Latch, enable	1.4		6	V
		Delay, hysteresis	V _S – 0.5		6	
V _{IL}	Low-level input voltage	Latch, enable	0		0.4	V
		Delay, hysteresis	0		0.5	
V _{OL}	Alert low-level output voltage	I _{OL} = 3 mA		50	400	mV
	$\overline{\text{ALERT}}$ terminal leakage input current	V _{OH} = 3.3 V		0.1	1	μA
	Digital leakage input current	0 ≤ V _{IN} ≤ V _S		1	2	μA
POWER SUPPLY						
I _Q	Quiescent current	V _{SENSE} = 0 mV, T _A = 25°C		115	135	μA
		T _A = –40°C to 125°C			150	
		V _{SENSE} = 0 mV, disable mode, HYS = 2 mV		2	3.5	

(1) RTI = referred-to-input.

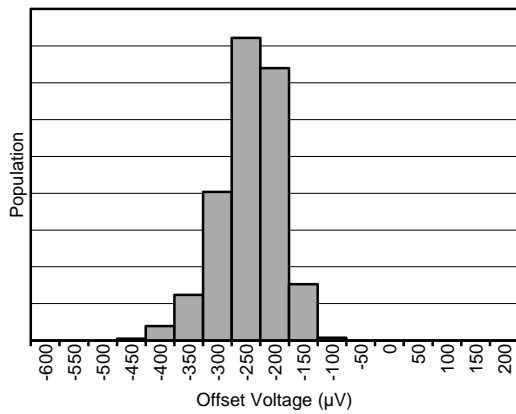
(2) Absolute-maximum values are tested with the threshold limit set using the corresponding noise adjustment factor (NAF) value. See [Noise Adjustment Factor \(NAF\)](#) for additional information on applying the NAF value.

6.6 Timing Requirements

	MIN	NOM	MAX	UNIT
Start-up time		1		ms
t_{en} Enable time		300		μs
t_{dis} Disable time		20		μs

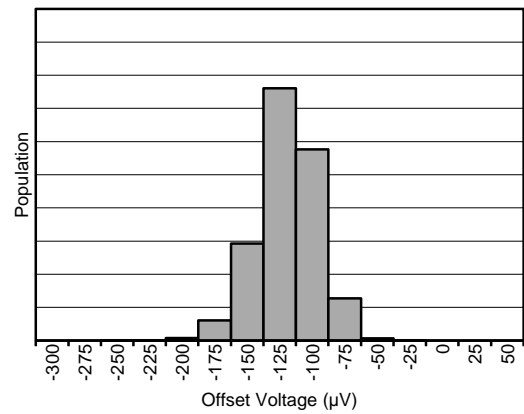
6.7 Typical Characteristics

at $T_A = 25^\circ\text{C}$, $V_S = 3.3\text{ V}$, $V_{IN+} = 12\text{ V}$, alert pull-up resistor = $10\text{ k}\Omega$, and Delay = $100\text{ }\mu\text{s}$ (unless otherwise noted)



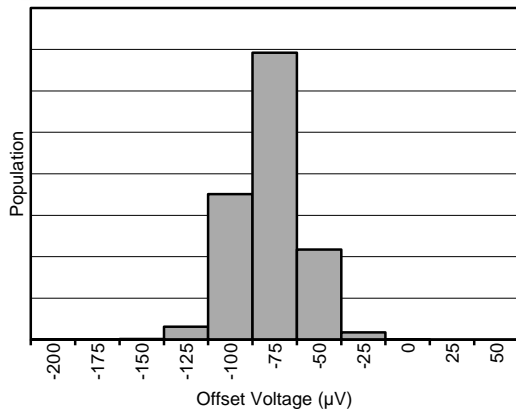
Delay = $10\text{ }\mu\text{s}$

Figure 1. Input Offset Voltage



Delay = $50\text{ }\mu\text{s}$

Figure 2. Input Offset Voltage



Delay = $100\text{ }\mu\text{s}$

Figure 3. Input Offset Voltage

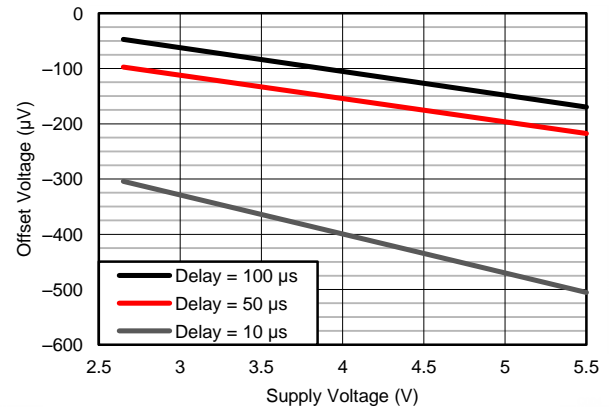


Figure 4. Input Offset Voltage vs Supply Voltage

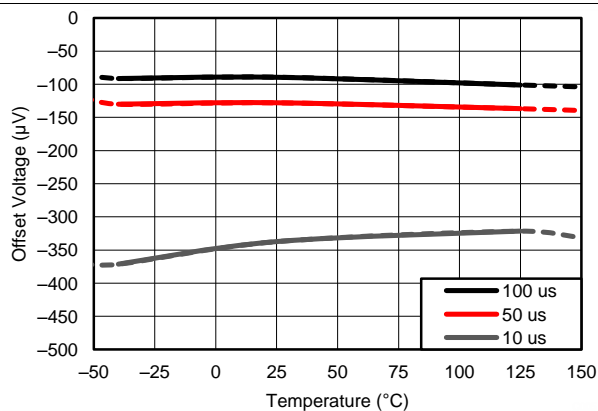


Figure 5. Input Offset Voltage vs Temperature

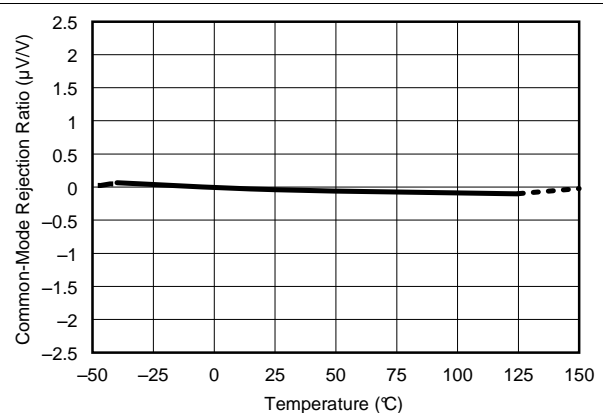


Figure 6. Common-Mode Rejection Ratio vs Temperature

Typical Characteristics (continued)

at $T_A = 25^\circ\text{C}$, $V_S = 3.3\text{ V}$, $V_{IN+} = 12\text{ V}$, alert pull-up resistor = $10\text{ k}\Omega$, and Delay = $100\text{ }\mu\text{s}$ (unless otherwise noted)

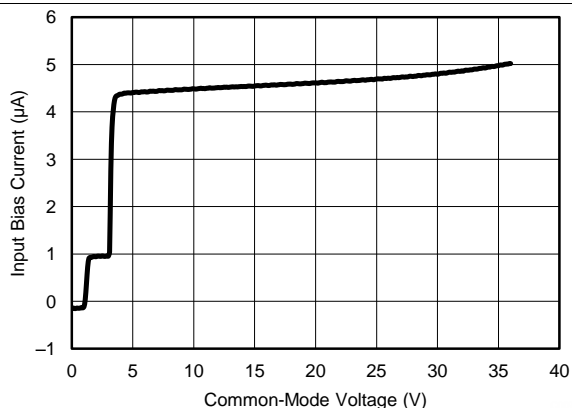


Figure 7. Input Bias Current vs Common-Mode Voltage (Enabled)

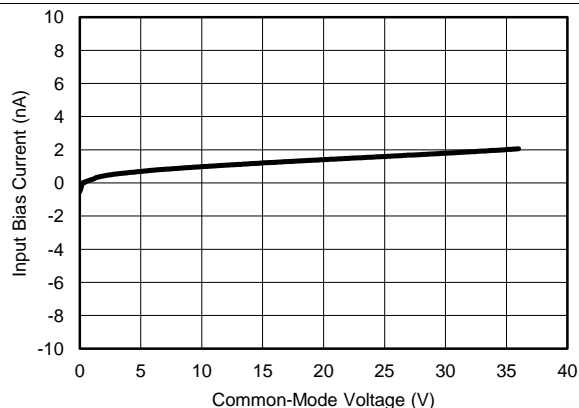


Figure 8. Input Bias Current vs Common-Mode Voltage (Disabled)

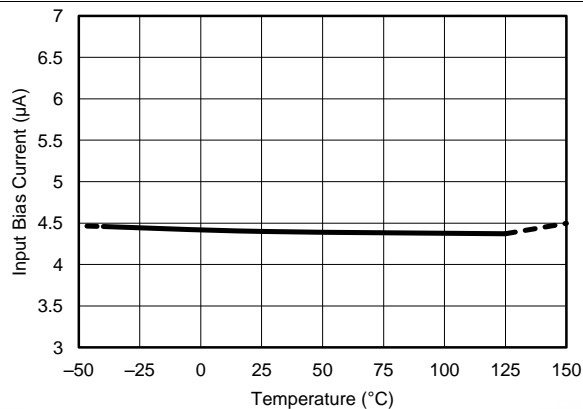


Figure 9. Input Bias Current vs Temperature (Enabled)

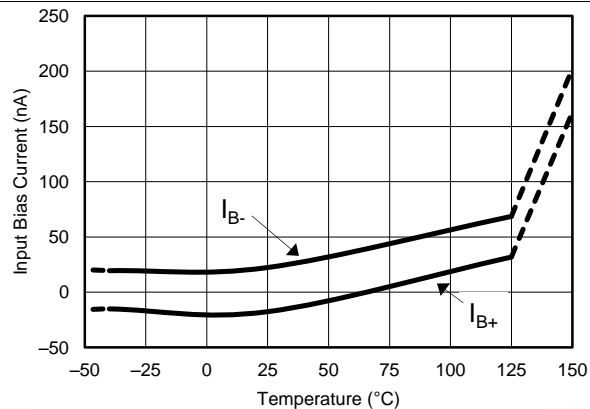


Figure 10. Input Bias Current vs Temperature (Disabled)

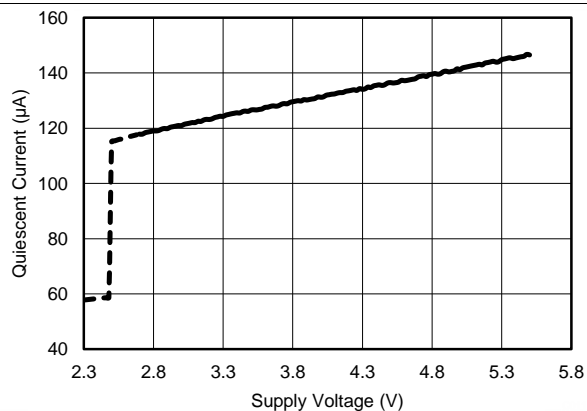


Figure 11. Quiescent Current vs Supply Voltage (Enabled)

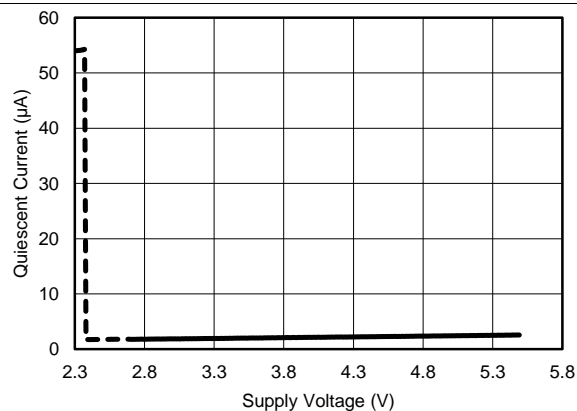


Figure 12. Quiescent Current vs Supply Voltage (Disabled)

Typical Characteristics (continued)

at $T_A = 25^\circ\text{C}$, $V_S = 3.3\text{ V}$, $V_{IN+} = 12\text{ V}$, alert pull-up resistor = 10 k Ω , and Delay = 100 μs (unless otherwise noted)

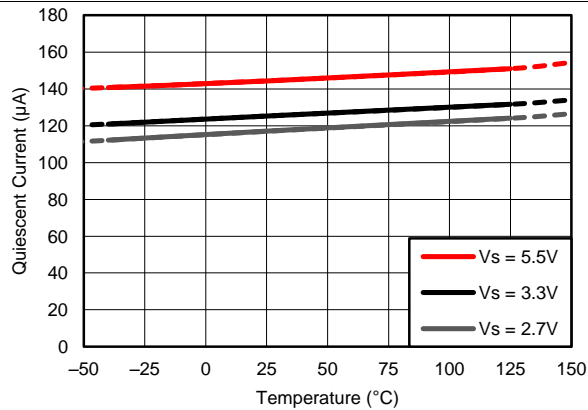


Figure 13. Quiescent Current vs Temperature (Enabled)

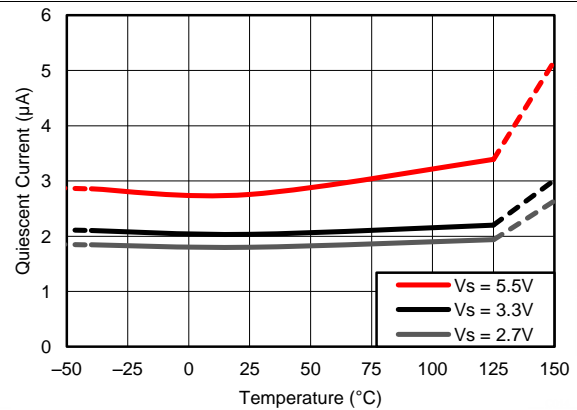


Figure 14. Quiescent Current vs Temperature (Disabled)

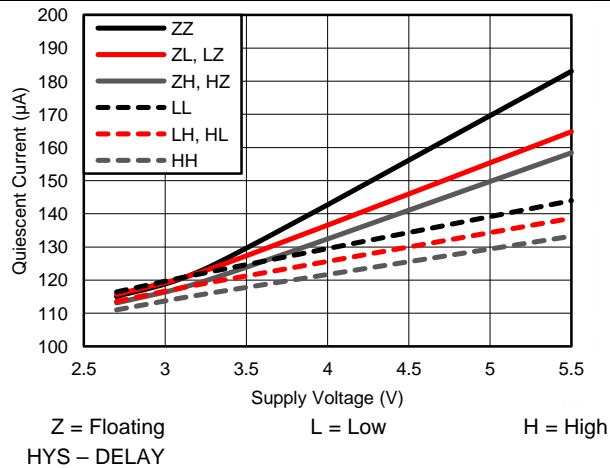


Figure 15. Quiescent Current vs HYS and DELAY Settings (Enabled)

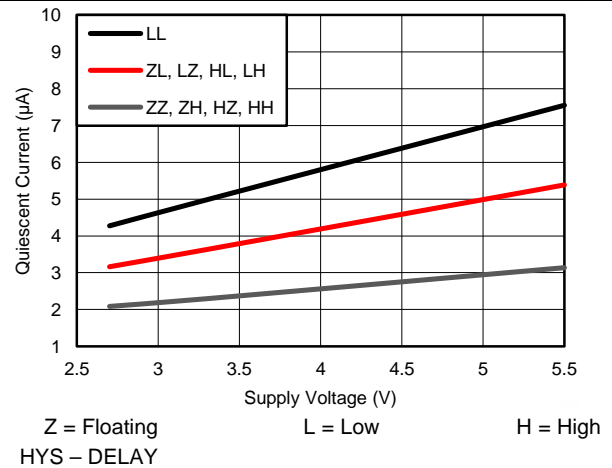


Figure 16. Quiescent Current vs HYS and DELAY Settings (Disabled)

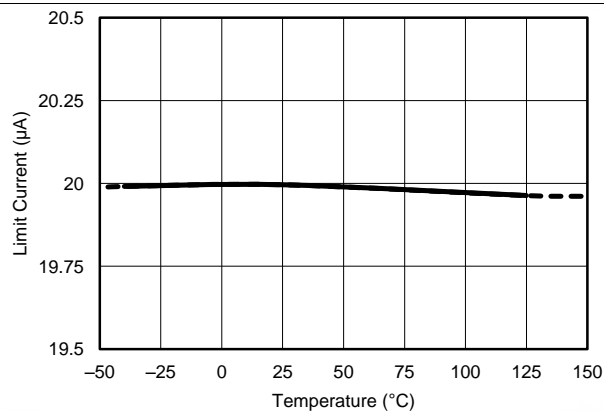


Figure 17. Limit Current Source vs Temperature

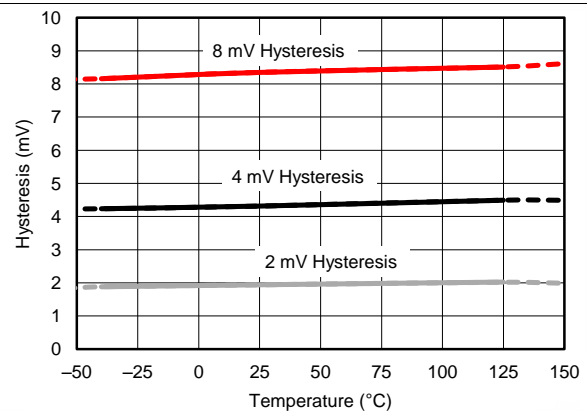


Figure 18. Hysteresis vs Temperature

Typical Characteristics (continued)

at $T_A = 25^\circ\text{C}$, $V_S = 3.3\text{ V}$, $V_{IN+} = 12\text{ V}$, alert pull-up resistor = $10\text{ k}\Omega$, and Delay = $100\text{ }\mu\text{s}$ (unless otherwise noted)

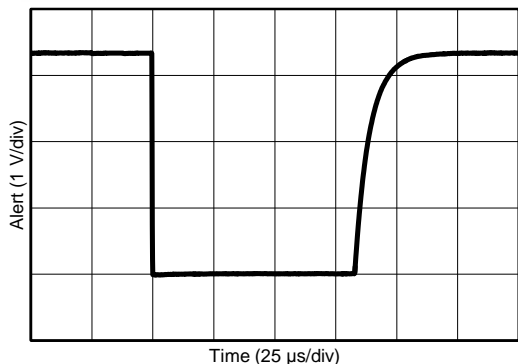


Figure 19. Alert Step Response

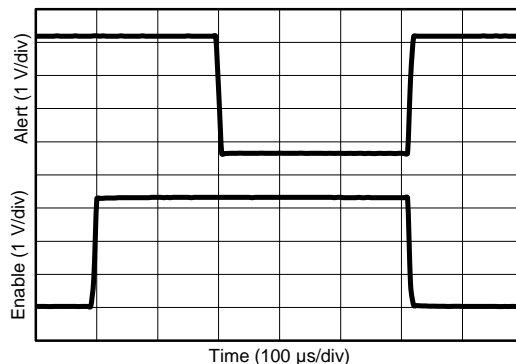
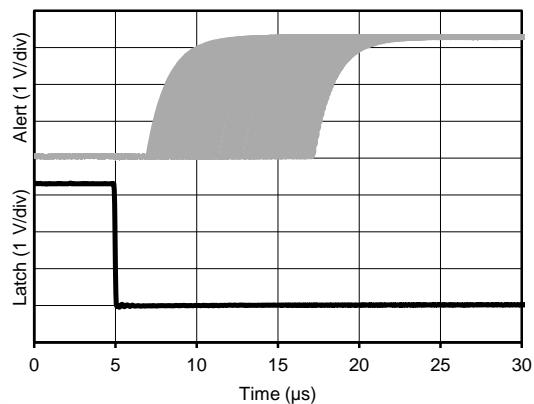


Figure 20. Alert Response (Disable to Enable)



**Figure 21. Alert Response
(Latch Mode to Transparent Mode)**

7 Detailed Description

7.1 Overview

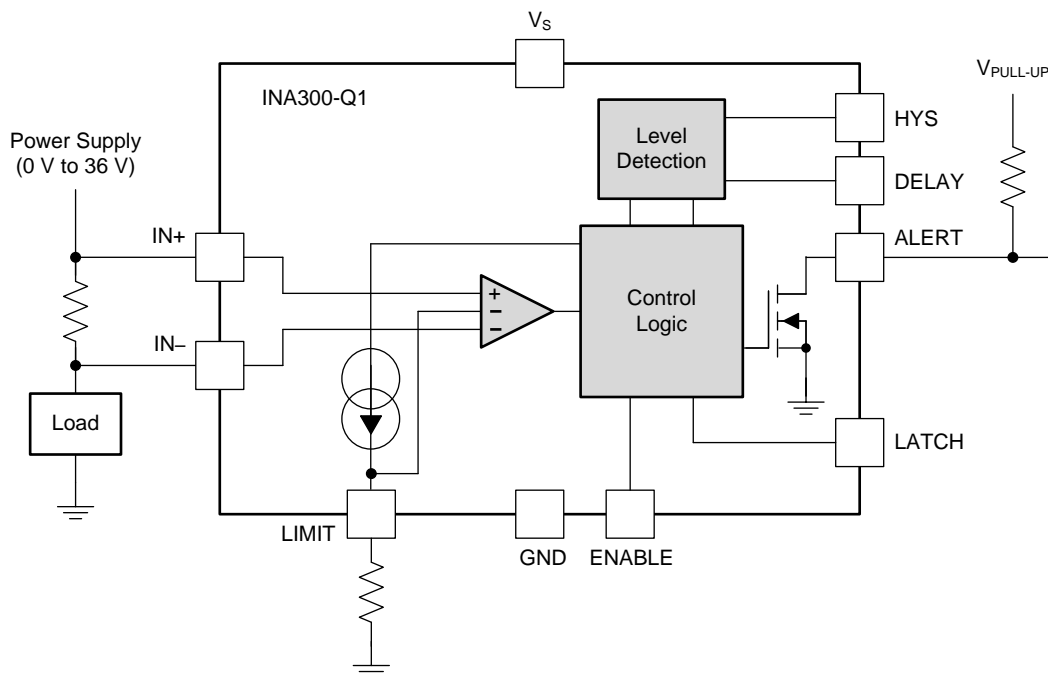
The INA300-Q1 is a 36-V, common-mode comparator designed for overcurrent protection applications. To reduce the system component count, this device combines the current-sense amplifier and threshold comparison into a single product for the overcurrent detection function. Programming this comparison threshold is configured through a single external resistor, which simplifies the current design while allowing for easy adjustments to the threshold when needed. The threshold setting resistor value is selected based on an internal 20- μ A current source to achieve a corresponding signal to the voltage that develops across the current-sensing or current-shunt resistor in series with the monitored load current.

The device is designed to accommodate a range of application requirements, including common-mode voltage, noise thresholds, and signal ranges. A wide signal threshold range reaching up to 250 mV is available to accommodate both power-sensitive applications requiring small dissipations across a current sense resistor and larger current-sensing resistors used in lower current applications.

Additional features available with the INA300-Q1 device include a disable mode for reducing the current consumption of the device to below 10 μ A, an output mode selector to enable a latched or transparent alert output, and a selectable hysteresis value and alert response delay.

The wide signal range of the device is further enhanced with an adjustable hysteresis value to adjust the characteristics of the comparator, which allows for better accommodation of the full input range. The selectable alert response delays present in the INA300-Q1 device assist in optimizing device operation to account for the system noise levels and operating characteristics required from this device. Longer delay settings allow for added rejection of system noise, thus reducing the potential for false alerts resulting from noise spikes that can occur in high-speed comparators.

7.2 Functional Block Diagram



Copyright © 2016, Texas Instruments Incorporated

7.3 Feature Description

7.3.1 Selecting a Current-Sensing Resistor

The device measures the differential voltage developed across a resistor when current flows through it to determine if the monitored current exceeds a defined limit. This resistor is referred to as a *current-sensing resistor* or a *current-shunt resistor*, with each term used interchangeably. The flexible design of the device allows for measuring a wide differential input signal range across this current-sensing resistor, which can extend up to 250 mV.

Selecting the value of this current-sensing resistor is based primarily on two factors: the required accuracy of the current measurement and the allowable power dissipation across the current-sensing resistor. Larger voltages developed across this resistor allow more accurate measurements. This large signal accuracy improvement results from the fixed internal amplifier errors that are dominated by the inherent input offset voltage of the device. When the input signal decreases, these fixed internal amplifier errors become a larger portion of the measurement and increase the uncertainty in the measurement accuracy. When the input signal increases, the measurement uncertainty is reduced because the fixed errors are a smaller percentage of measured signal.

A system design trade-off for improving the measurement accuracy using larger input signals is the increase in power across the current-sensing resistor. Increasing the value of the current-shunt resistor increases the differential voltage developed across the resistor when current passes through the component. This increase in voltage across the resistor increases the power that the resistor must be able to dissipate. Decreasing the value of the current-shunt resistor value reduces the power dissipation requirements of the resistor, but increases the measurement errors resulting from the decreased input signal. Selecting the optimal value for the shunt resistor requires factoring both the accuracy requirement for the specific application and the allowable power dissipation of this component.

An increasing number of low ohmic-value resistors are becoming available with values as low as 200 $\mu\Omega$, with power dissipations of up to 5 W that enable large currents to be monitored with sensing resistors.

7.3.1.1 Selecting a Current-Sensing Resistor: Example

In this example, the trade-offs involved in selecting a current-sensing resistor are discussed. This example requires a 5% measurement accuracy for detecting a 10-A overcurrent event at a 50- μs delay setting where only 250 mW is allowable for the dissipation across the current-sensing resistor at the full-scale current level. Although the maximum power dissipation is defined as 250 mW, a lower dissipation is preferred to improve system efficiency. Some initial assumptions are made that are used in this example: the limit setting resistor, R_{LIMIT} , is a 1% component and the maximum tolerance specification for the internal threshold setting current source, 0.5%, is used. Given the total error budget of 5%, up to 3.5% of error is available to be attributed to the internal offset of the device.

Feature Description (continued)

As shown in Table 1, the maximum value calculated for the current-sensing resistor with these requirements is 2.5 mΩ. Although this value satisfies the maximum power dissipation requirement of 250 mW, headroom is available from the 5% maximum total error to reduce the value of the current-sensing resistor and reduce the power dissipation further. Selecting a 1.5-mΩ, current-sensing resistor value offers a tradeoff for reducing the power dissipation in this scenario by approximately 40%, while still remaining within the defined accuracy region.

Table 1. Calculating the Current-Sensing Resistor, R_{SENSE}

PARAMETER	EQUATION	VALUE	UNIT
Maximum measurement error		5%	
I_{MAX}	Maximum current	10	A
P_{RSENSE}	Maximum allowable R_{SENSE} power dissipation	$R_{SENSE} \times I_{MAX}^2$	mW
	Initial error	$R_{LIMIT} + I_{LIMIT}$ tolerances	1.5%
R_{SENSE_MAX}	Maximum sensing resistor value	P_{RSENSE} / I_{MAX}^2	mΩ
V_{SENSE_MAX}	Input sense voltage	$R_{SENSE_MAX} \times I_{MAX}$	mV
V_{OS} Error	Offset voltage error	$(V_{OS} / V_{SENSE_MAX}) \times 100$	2%
Error_Available	Maximum allowable offset error	Maximum Error – Initial Error	3.5%
V_{SENSE_MIN}	Minimum input sense voltage	$V_{OS} / (\text{Error_Available} / 100)$	mV
R_{SENSE_MIN}	Minimum sensing resistor value	V_{SENSE_MIN} / I_{MAX}	mΩ
P_{RSENSE_MIN}	Minimum power dissipation	$R_{SENSE_MIN} \times I_{MAX}^2$	mW

7.3.2 Setting The Current-Limit Threshold

The device determines if an overcurrent event is present by comparing the measured differential voltage developed across the current-sensing resistor to the corresponding signal programmed at the LIMIT terminal. The threshold voltage for the LIMIT terminal can be set using a resistor or an external voltage source.

7.3.2.1 Resistor-Controlled Current Limit

The typical approach for setting the limit threshold voltage is to connect a resistor from the LIMIT terminal to ground. The value of this resistor, R_{LIMIT} , is chosen to create a corresponding voltage at the LIMIT terminal equivalent to the voltage, V_{TRIP} , developed by the load current flowing through the current-sensing resistor. An internal 20-μA current source is present at the LIMIT terminal that creates the corresponding voltage depending on the value of R_{LIMIT} . In the equations from Table 2, V_{TRIP} represents the overcurrent threshold the device is programmed to monitor for and V_{LIMIT} is the programmed signal set to detect the V_{TRIP} level. The term *noise adjustment factor* (NAF) is included in the V_{LIMIT} equation for the 10-μs delay setting. This value is equal to 500 μV and adjusts the operating point for the internal noise in this delay setting. The 50-μs and 100-μs delay settings do not use the NAF term in calculating the V_{LIMIT} threshold. See [Noise Adjustment Factor \(NAF\)](#) for more details on the noise adjustment factor.

In Table 2, the process for calculating the required value for R_{LIMIT} to set the appropriate threshold voltage, V_{LIMIT} , is shown. This calculation is based on the 10-μs delay setting so the NAF term is included in the calculation. For a delay setting of 50 μs or 100 μs, the NAF term is omitted.

Table 2. Calculating the Limit Threshold Setting Resistor, R_{LIMIT}

PARAMETER	EQUATION
V_{TRIP}	Desired current trip value
V_{LIMIT}	Programmed threshold limit voltage
$V_{LIMIT}^{(1)}$	Threshold voltage
$R_{LIMIT}^{(1)}$	Threshold limit setting resistor
$R_{LIMIT}^{(1)}$	Limit setting resistor

(1) NAF is used with the 10-μs delay setting. NAF can be omitted in the R_{LIMIT} calculation for the 50-μs and 100-μs delay settings.

TI recommends using NAF in calculating the value for V_{LIMIT} and R_{LIMIT} at the 10- μ s delay setting. Removing NAF from the V_{LIMIT} and R_{LIMIT} calculation at the 10- μ s delay setting lowers the trigger point of the alert output. Lowering the trigger point results in the device issuing an overcurrent alert prior to reaching the corresponding V_{TRIP} threshold. The averaging effect included with the 50- μ s and 100- μ s delay settings inherently eliminates the effect internal noise has on the threshold voltage.

7.3.2.2 Voltage Source Controlled Current Limit

The second method for setting the limit voltage is to connect the LIMIT terminal to a programmable DAC (digital-to-analog converter) or other external voltage source. The benefit of this method is the ability to adjust the current limit to account for different threshold voltages that are used for different system operating conditions. For example, this method can be used in a system that has one current-limit threshold level that must be monitored during the power-up sequence but different thresholds must be monitored during other system operating modes.

In Table 3, V_{TRIP} represents the overcurrent threshold the device is programmed to monitor for and V_{SOURCE} is the programmed signal set to detect the V_{TRIP} level. NAF is included in the V_{SOURCE} equation for the 10- μ s delay setting. This value equals 500 μ V and is adjusts the operating point for the noise in the delay setting. The 50- μ s and 100- μ s delay settings do not use the NAF term in calculating the V_{SOURCE} threshold. For these delay settings, the NAF term is omitted. See the [Noise Adjustment Factor \(NAF\)](#) section for more details on the noise adjustment factor.

Table 3. Calculating the Limit Threshold Voltage Source, V_{SOURCE}

PARAMETER		EQUATION
V_{TRIP}	Desired current trip value	$I_{LOAD} \times R_{SENSE}$
$V_{SOURCE}^{(1)}$	Programmed threshold limit voltage	$V_{TRIP} + NAF$
$V_{SOURCE}^{(1)}$	Programmed signal set to detect the V_{TRIP} level	$V_{TRIP} + 500 \mu V$

(1) NAF is used with the 10- μ s delay setting. NAF can be omitted in the V_{SOURCE} calculation for the 50- μ s and 100- μ s delay settings.

TI recommends using NAF in calculating the value for V_{SOURCE} at the 10- μ s delay setting. Removing NAF from the V_{SOURCE} calculation at the 10- μ s delay setting lowers the trigger point of the alert output. Lowering the trigger point results in the device issuing an overcurrent alert prior to reaching the corresponding V_{TRIP} threshold. The averaging effect included with the 50- μ s and 100- μ s delay settings inherently eliminates the effect internal noise has on the threshold voltage.

7.3.3 Delay Setting

The device response time for overcurrent events is adjustable based on the DELAY terminal setting. Three response time settings are available, ranging from 10 μ s to 100 μ s. The primary purpose for the three different delay settings is to offer a trade-off between a faster alert response and a more precise overcurrent threshold level detection.

The device has a 10- μ s internal comparison window. This single comparison window is the fundamental time unit used for all three delay settings. For the 10- μ s delay setting, the device compares the average of the input signal during the 10- μ s comparison window to the threshold limit programmed at the LIMIT terminal. If the averaged input signal exceeds the threshold at the end of the 10- μ s comparison window, the output alert triggers and pulls the \overline{ALERT} terminal low. However, if the averaged input does not exceed the threshold at the end of the 10- μ s comparison window, there is no change in the output alert status, which remains high to indicate that no overcurrent event is detected.

For the 50- μ s delay setting, there must be five consecutive 10- μ s comparison windows that result in an average input signal exceeding the threshold limit in order for the output alert to trigger and pull the \overline{ALERT} terminal low. If any single 10- μ s comparison window fails to detect an overcurrent condition before reaching five consecutive overcurrent comparisons, the internal counter is reset and no output alert is issued. With the internal counter reset, a new group of five consecutive 10- μ s comparison windows of overcurrent conditions are required in order to trigger the alert and pull the \overline{ALERT} terminal low.

The 100- μ s delay setting operates in the same manner as the 50- μ s method, but instead requires ten consecutive 10- μ s comparison windows with an input signal exceeding the threshold limit to issue an output alert and pull the \overline{ALERT} terminal low.

Requiring multiple consecutive overcurrent detections aids significantly in reducing the likelihood of system noise causing false alerts, which can be detrimental to critical system operations. However, by enabling an alert window equal to the comparison window of 10 μs , the device still has the flexibility to be used in fast overcurrent detection applications that require quick responses to rapidly changing system operating characteristics.

In Figure 22, the device alert output response is shown for a 10- μs delay setting and a 50- μs delay setting based on the same input signal condition. The initial increase of the input signal, V_{IN} , above the V_{LIMIT} level remains above the limit for approximately 30 μs . With the device set to the 10- μs delay setting, the overcurrent condition is detected and the alert output terminal is pulled low approximately 10 μs later. With the device set to the 50- μs delay setting, an alert is not issued because five consecutive 10- μs overcurrent measurements are not detected. With the input signal only being over the limit for 30 μs rather than the corresponding 50 μs needed for this delay setting, the device does not issue an alert under this condition. For the second instance where V_{IN} rises above the V_{LIMIT} threshold, the input remains above the limit for more than five consecutive 10- μs measurements, indicating an overcurrent condition and the alert output terminal is pulled low.

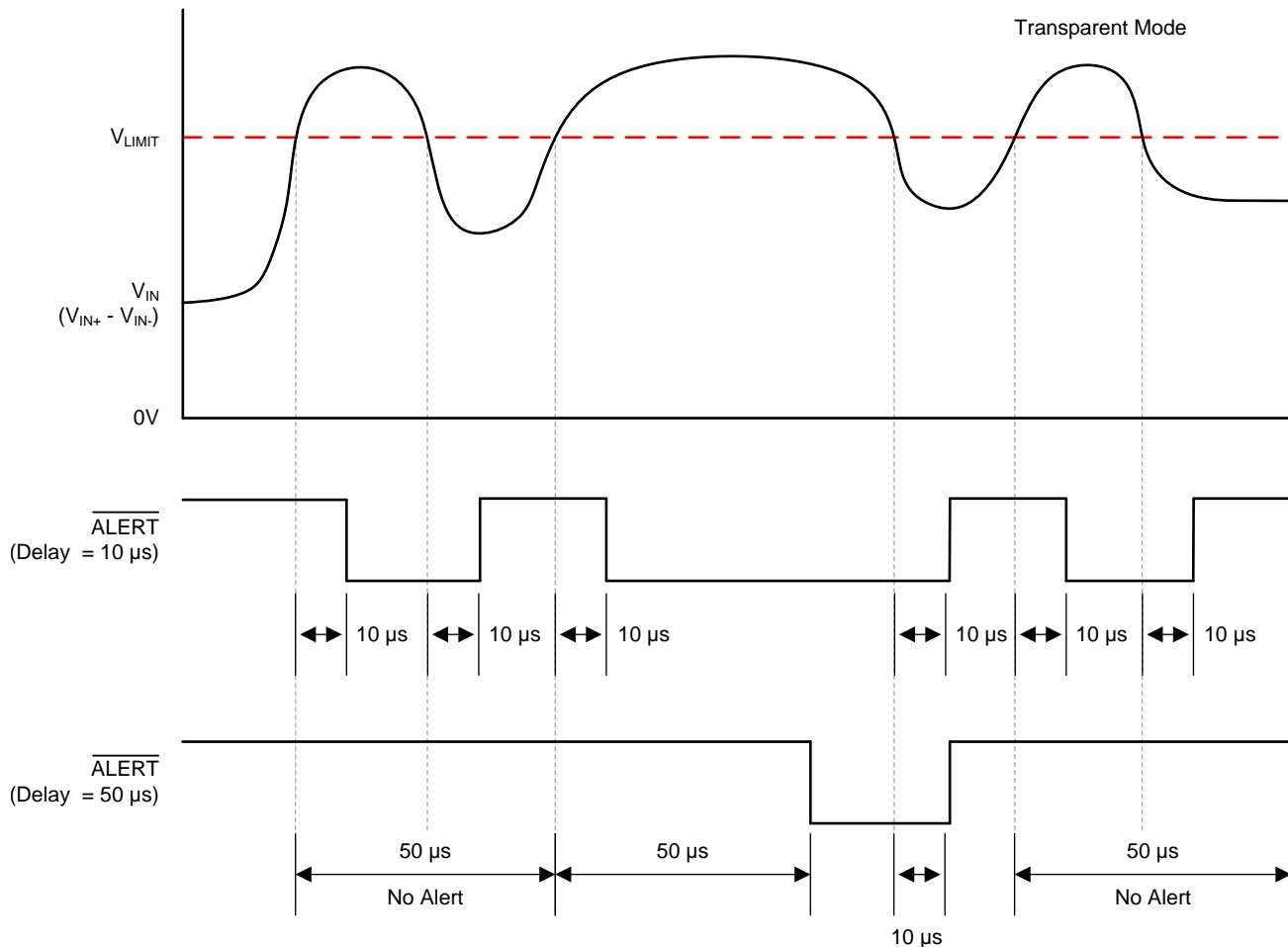


Figure 22. DELAY Terminal Settings

As discussed previously, there are three different available delay settings that are configured based on the signal connected to the DELAY terminal, as shown in Figure 23 and Table 4. The DELAY terminal must be either connected directly to ground, directly to supply, or left completely floating. Additional external resistors must not be connected to this terminal. If a resistance is required by the application to be placed in series with either the supply or ground connection to the DELAY terminal, this resistance must be limited to 1 k Ω so as to not conflict with the internal level-detection circuitry.

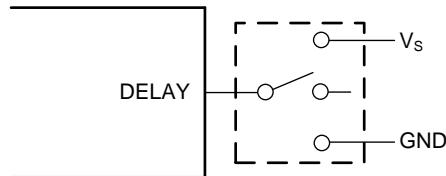


Figure 23. Delay Response

Table 4. Delay Settings

DELAY	ALERT DELAY (μ s)
Open or floating	10
GND	50
V _S	100

7.3.4 Alert Timing Response

The device has a 10- μ s internal comparison window where the input signal is measured to compare to the limit threshold voltage. This window continuously runs internal to the device without any external indicator or control. A comparison is made at the completion of each 10- μ s comparison window to determine if the averaged input over the comparison window exceeds the limit threshold, thus indicating if an overcurrent event has occurred.

This comparison window is not synchronized with the input signal so there is an unknown timing component present. With this free-running internal timing window, an overcurrent event can occur anywhere within the 10- μ s comparison window. This condition causes a variation in the amount of time before the alert appears at the output because the comparison is always made at the end of the 10- μ s comparison window. Figure 24 shows the variation in time between when the input signal rises above the threshold voltage and when a change at the alert output terminal occurs.

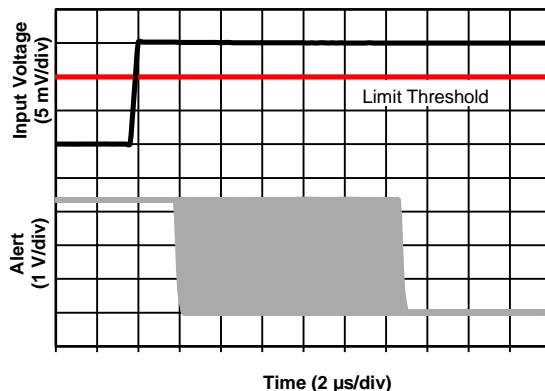
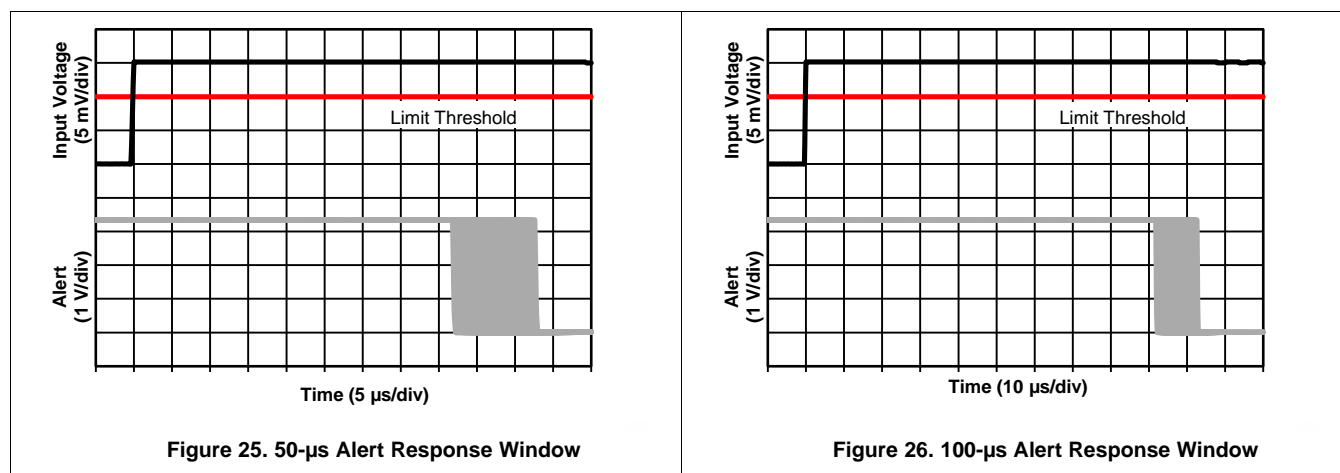


Figure 24. 10- μ s Alert Response Window

The delay shown in [Figure 24](#) represents the response time of the device with a 10- μ s delay setting. With a 50- μ s delay setting, an additional 40 μ s is added to the timing response, as shown in [Figure 25](#). A 100- μ s delay setting adds 90 μ s to the response time, as shown in [Figure 26](#).



7.3.5 Selectable Hysteresis

Device hysteresis is adjustable based on the setting at the hysteresis (HYS) terminal. The smallest setting for hysteresis on the device, 2 mV, is enabled by leaving the HYS terminal open and floating. A 4-mV hysteresis is set by connecting the HYS terminal to ground; connecting this terminal to the supply voltage sets the hysteresis to 8 mV, as shown in [Figure 27](#). The HYS terminal must be either connected directly to ground, directly to supply, or left completely floating. Additional external resistors must not be connected to this terminal. If a resistance is required by the application to be placed in series with either the supply or ground connections to the HYS terminal, this resistance must be limited to 1 k Ω so as to not conflict with the internal level-detection circuitry.

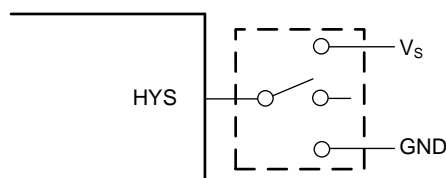


Figure 27. Delay Response

The wide dynamic input range of the INA300-Q1 necessitates an adjustable hysteresis to ensure that the device can be appropriately configured based on the specific operating conditions and application requirements. Figure 28 illustrates the transition locations for the ALERT terminal based on where the input signal, V_{IN} , is measured relative the limit threshold, V_{LIMIT} . The corresponding hysteresis levels and physical terminal settings for the device are shown in Table 5.

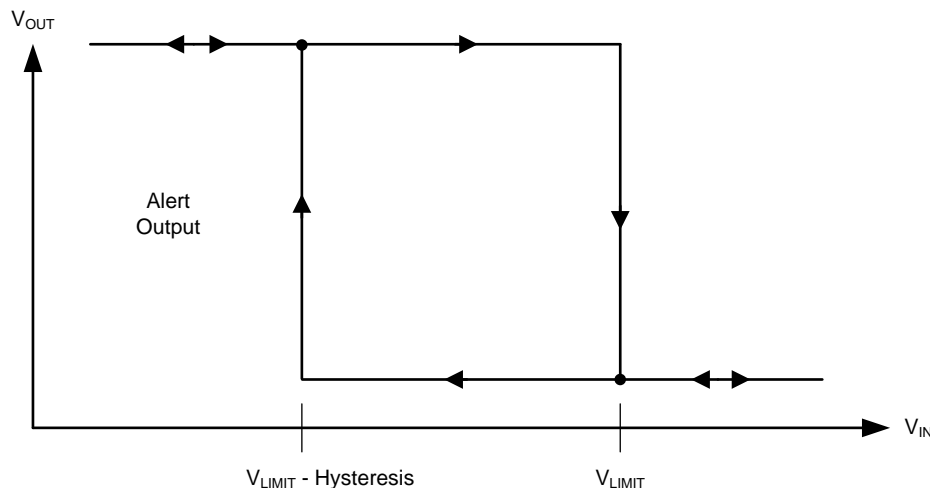


Figure 28. Typical Comparator Hysteresis

Table 5. Hysteresis Settings

HYSTERESIS	HYSTERESIS SETTING
Float	2 mV
GND	4 mV
V_S	8 mV

7.3.6 Alert Output

The device $\overline{\text{ALERT}}$ terminal is an active-low, open-drain output. This output is designed to be pulled low when the input conditions are detected as out-of-range. This open-drain output pin is recommended to include a 10-k Ω , pull-up resistor to the supply voltage. This open-drain terminal can be pulled up to a voltage beyond the supply voltage, V_S , but must not exceed 5.5 V.

7.3.7 Noise Adjustment Factor (NAF)

The device is a high-speed, low-noise comparator that is designed to alert when the measured input signal exceeds the programmed limit level. Internal noise in the device couples into the measurement and can result in alerts being issued prior to the input signal exceeding the voltage level present at the LIMIT terminal. This known internal noise component effects the input signal measurement by causing a consistent shift in the device internal offset, resulting in a shifted trip threshold. NAF adjusts the V_{LIMIT} setting to account for this internal shift, thus allowing for a more precise level detection of the measured current.

The NAF value is based on the noise contribution on the measurement at the 10- μs delay setting. This value is equal to 500 μV and is applied in the calculation to adjust the V_{LIMIT} threshold level to allow for a more accurate alert trip point. The NAF term is only applied in the V_{LIMIT} calculation at the 10- μs delay setting. The averaging effect included with the 50- μs and 100- μs delay settings inherently eliminates the effect internal noise has on the threshold voltage. The NAF term can be omitted from the R_{LIMIT} calculation at the 10- μs delay setting with the effect of a lower trigger point of the alert output. Lowering the trigger point results in an overcurrent alert prior to reaching the corresponding V_{TRIP} threshold.

7.4 Device Functional Modes

7.4.1 Alert Mode

The device has two output operating modes that are selected based on the LATCH terminal setting: transparent mode and latch mode. These modes change how the $\overline{\text{ALERT}}$ terminal responds to the changing input signal conditions.

7.4.1.1 Transparent Output Mode

The device is set to transparent mode when the LATCH terminal is pulled low, thus allowing the output alert state to change and follow the input signal with respect to the programmed alert threshold. For example, when the differential input signal rises above the alert threshold, the alert output terminal is pulled low. When the differential input signal drops below the alert threshold for 10 μs , the output returns to the default high output state. A common implementation using the device in transparent mode is to connect the $\overline{\text{ALERT}}$ terminal to a hardware interrupt input on a controller. As soon as an overcurrent condition is detected in the device and the $\overline{\text{ALERT}}$ terminal is pulled low, the controller interrupt terminal detects the output state change and can begin making changes to the system operation needed to address the overcurrent condition.

7.4.1.2 Latch Output Mode

Some applications do not have the functionality available to continuously monitor the state of the output $\overline{\text{ALERT}}$ terminal to detect an overcurrent condition. A typical example of this application is a system that is only able to poll the $\overline{\text{ALERT}}$ terminal state periodically to determine if the system is functioning correctly. If the device is set to transparent mode in this type of application, missing the change in state of the $\overline{\text{ALERT}}$ terminal is possible when $\overline{\text{ALERT}}$ is pulled low to indicate an out-of-range event if the out-of-range condition does not appear during one of these periodic polling events.

Latch mode is specifically intended to accommodate these applications. As shown in Table 6, the device is placed in latch mode by setting the voltage on the LATCH terminal to a logic high level. The difference between latch mode and transparent mode is how the alert output responds when an overcurrent event ends. In transparent mode, when the differential input signal drops below the limit threshold level for 10 μs , the output state returns to the default high setting to indicate that the overcurrent event had ended.

In latch mode, when an overlimit condition is detected and the $\overline{\text{ALERT}}$ terminal is pulled low, the $\overline{\text{ALERT}}$ terminal does not return to the default high level when the differential input signal drops below the alert threshold level for 10 μs . To clear the alert the LATCH terminal must be pulled low for at least 20 μs . Pulling the LATCH terminal low allows the $\overline{\text{ALERT}}$ terminal to return to the default high level, provided that the differential input signal has dropped below the alert threshold. If the input signal is still above the threshold limit when the LATCH terminal is pulled low, the $\overline{\text{ALERT}}$ terminal remains low. When the alert condition is detected by the system controller (the LATCH terminal) can be set back to high in order to place the device back in latch mode.

Table 6. Output Mode Settings

OUTPUT MODE	LATCH TERMINAL SETTING
Transparent mode	LATCH = low
Latch mode	LATCH = high

The latch and transparent modes are represented in Figure 29. In Figure 29 when V_{IN} drops back below the V_{LIMIT} threshold for the first time, the LATCH terminal is pulled high. With the LATCH terminal pulled high, the device is set to latch mode so that the alert output state does not return high when the input signal drops below the V_{LIMIT} threshold. Only when the LATCH terminal is pulled low does the ALERT terminal return to the default high level, indicating that the input signal is below the limit threshold. When the input signal drops below the limit threshold for the second time, the LATCH terminal is already pulled low. The device is set to transparent mode at this point and the ALERT terminal is pulled back high when the input signal drops below the alert threshold.

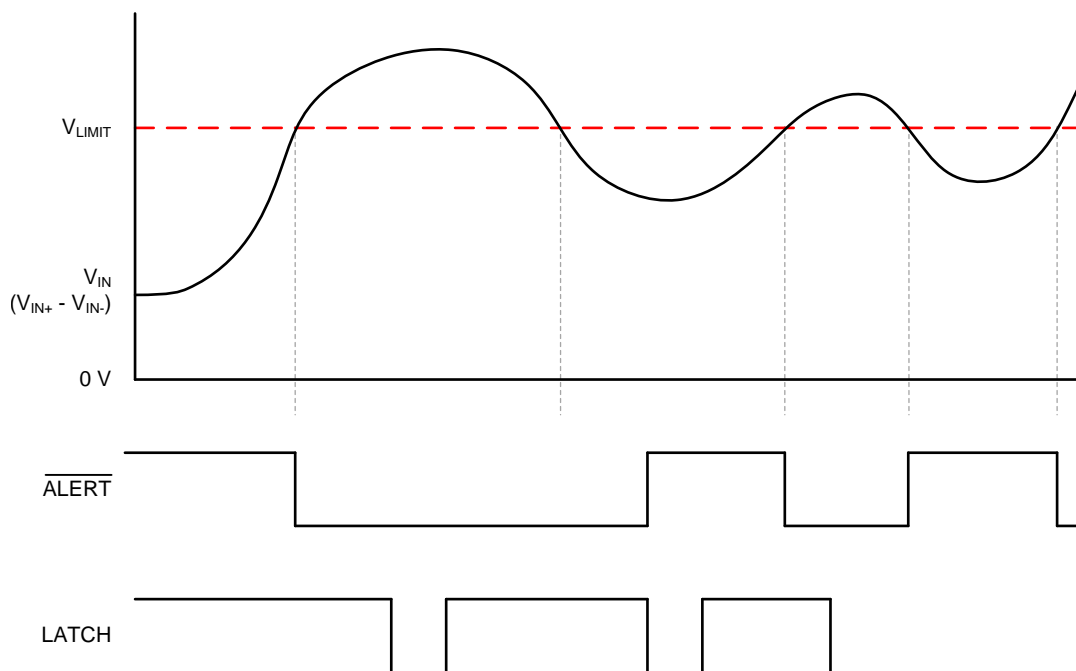


Figure 29. Transparent vs Latch Mode

7.4.2 Disable Mode

The INA300-Q1 device has an ENABLE terminal that allows the device to be placed into an active enabled state or a low-power disabled state where less than 10 μ A is consumed from all terminals. This disable state allows the device to be used in applications where low current consumption is required to extend battery life where constant monitoring is not required. The INA300-Q1 device requires approximately 20 μ s to enter the low-power state when the ENABLE terminal transitions from high to low, as shown in Table 7. To return to the enabled active state, the INA300-Q1 device requires approximately 300 μ s to return to normal operation when the ENABLE terminal transitions from low to high, taking the device out of the low-power state.

Table 7. Enable and Disable Mode Settings

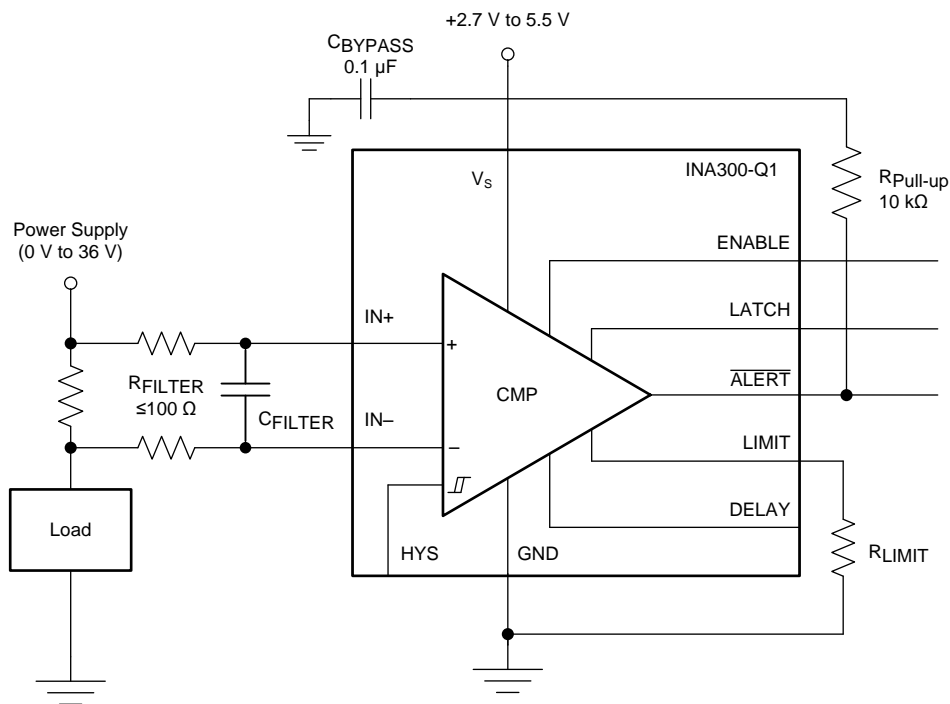
ENABLE MODE	ENABLE TERMINAL SETTING
Disable mode	ENABLE = low
Enable mode	ENABLE = high

The internal counter that determines if the necessary consecutive 10- μ s window comparison alert conditions are reached for the 50- μ s and 100- μ s delay setting is reset when the device is put into a disabled state. When the device is re-enabled, the counter restarts.

7.4.3 Input Filtering

External system noise can have a significant effect in the ability of a comparator to accurately measure and detect whether input signals exceed the reference threshold levels, indicating an overrange condition. The device is susceptible to external noise, although the 50- μ s and 100- μ s delay settings are can mitigate the impact of noise based on the effective averaging achieved in these modes. The obvious effect that external noise can have on the operation of a comparator is to cause a false alert condition. If a comparator detects a large noise transient coupled into the signal, the device can interpret this transient as an overrange condition.

External filtering can help reduce the amount of noise that reaches the comparator inputs, and can reduce the likelihood of a false alert from occurring. The tradeoff to adding this noise filter is increased comparator response time, because of the input signal being filtered as well as the noise. [Figure 30](#) shows the implementation of an input filter for the device.



Copyright © 2016, Texas Instruments Incorporated

Figure 30. Input Filter

Limiting the amount of input resistance used in this filter is important because this resistance can have a significant effect on the input signal that reaches the device input pins resulting from the device input bias currents. A typical system implementation involves placing the current-sensing resistor near the device so the traces are short and the trace impedance is small. This layout helps reduce the ability of coupling additional noise into the measurement. Under these conditions, the characteristics of the input bias currents have minimal effect on device performance.

As shown in [Figure 31](#), the input bias currents increase in opposite directions when the differential input voltage increases. This increase results from the design of the device, which allows common-mode input voltages to far exceed the device supply voltage range. With input filter resistors now placed in series with these unequal input bias currents, there are unequal voltage drops developed across the input resistors. The difference between the two drops appears as an added signal that (in this case) subtracts from the voltage developed across the current-sensing resistor, reducing the signal that reaches the device input terminals. Smaller value input resistors reduce this effect of signal attenuation to allow for a more accurate measurement.

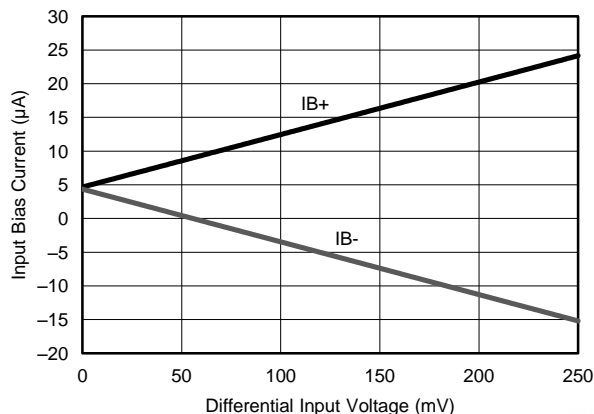


Figure 31. Input Bias Current vs Differential Input Voltage

For example, with a differential voltage of 10 mV developed across a current-sensing resistor and using 100- Ω resistors, the differential signal that reaches the device is 9.8 mV. A measurement error of 2% is created as a result of the external input filter resistors. Using 10- Ω input filter resistors instead of the 100- Ω resistors reduces this added error from 2% to 0.2%.

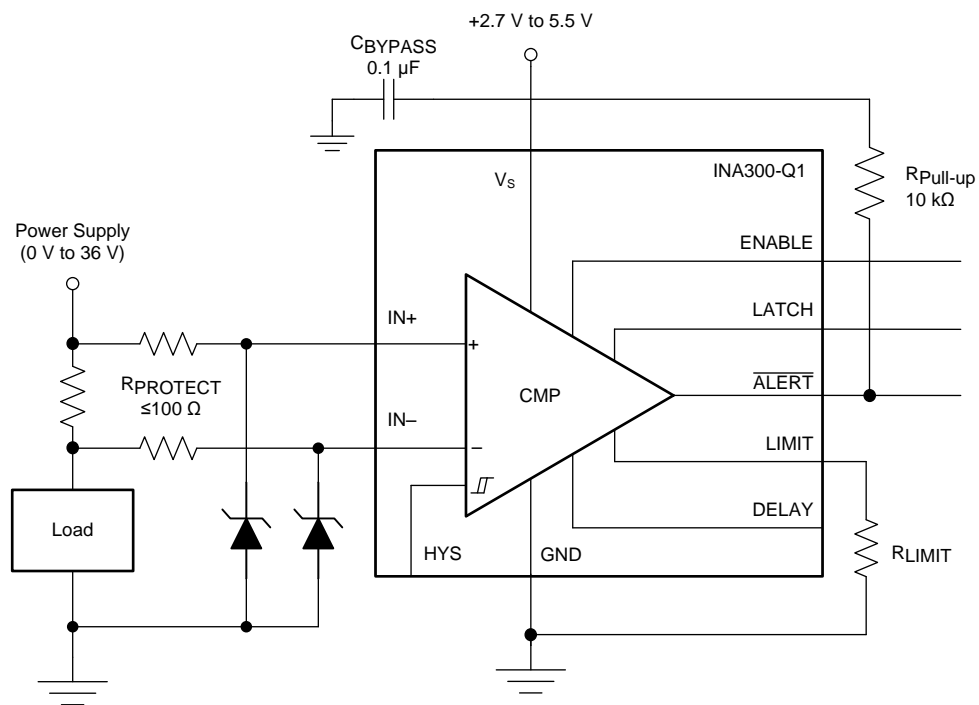
7.4.4 Using the INA300-Q1 With Common-Mode Transients Above 36 V

With a small amount of additional circuitry, the device can be used in circuits subject to transients higher than 36 V. Use only zener diodes or zener-type transient absorbers (sometimes referred to as *Transzorbs*). Any other type of transient absorber has an unacceptable time delay. Start by adding a pair of resistors, as shown in [Figure 32](#), as a working impedance for the zener diode. Keeping these resistors as small as possible is best, preferably 100 Ω or less. Larger values can be used with an additional error induced resulting from a reduced signal that reaches the device input terminals. Because this circuit limits only short-term transients, many applications are satisfied with a 100- Ω resistor along with conventional zener diodes of the lowest power rating available. This combination uses the least amount of board space. These diodes can be found in SOT-523 or SOD-523 packages.

INA300-Q1

ZHCSEX8A – DECEMBER 2015 – REVISED OCTOBER 2016

www.ti.com.cn



Copyright © 2016, Texas Instruments Incorporated

Figure 32. Transient Protection

8 Applications and Implementation

NOTE

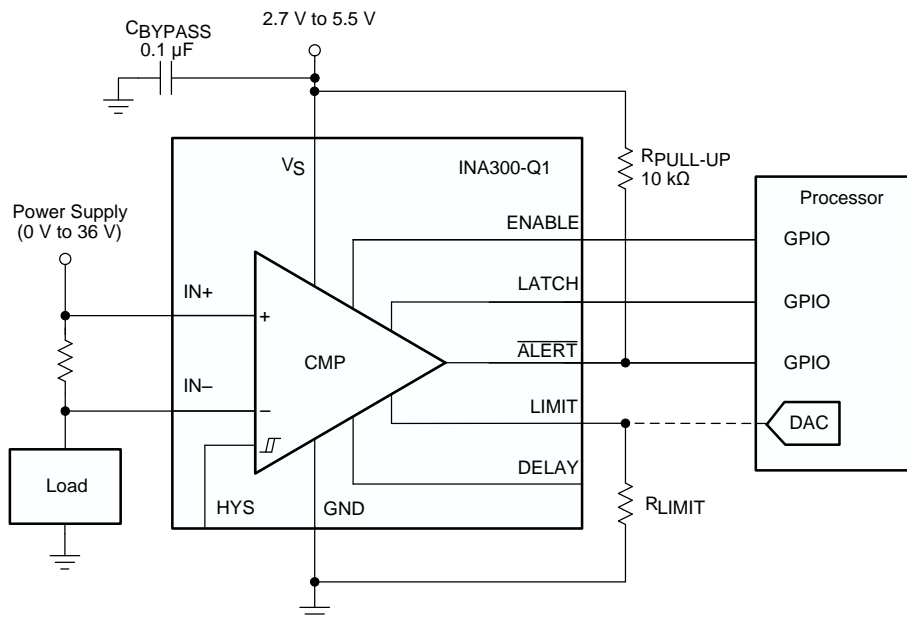
Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The INA300-Q1 is designed to enable configuration for detecting overcurrent conditions in an application. This device is individually targeted towards overcurrent detection of a single threshold. However, this device can be paired with additional devices and circuitry to create more complex monitoring functional blocks.

8.2 Typical Applications

8.2.1 Unidirectional Operation



Copyright © 2016, Texas Instruments Incorporated

Figure 33. Unidirectional Application Schematic

8.2.1.1 Design Requirements

The INA300-Q1 device measures current through a resistive shunt with current flowing in one direction, enabling detection of an overcurrent event only when the differential input voltage exceeds the threshold limit.

8.2.1.2 Detailed Design Procedure

Figure 33 shows the basic connections of the INA300-Q1 device. The input terminals, IN+ and IN–, must be connected as closely as possible to the current-sensing resistor to minimize any resistance in series with the shunt resistance. Additional resistance between the current-sensing resistor and input terminals can result in errors in the measurement. When input current flows through this external input resistance, the voltage developed across the shunt resistor can differ from the voltage reaching the input terminals.

Typical Applications (continued)

8.2.1.3 Application Curve

Figure 34 shows the alert response transitioning from a high to a low state following the input signal exceeding the limit threshold voltage. The time required for the output to respond varies as a result of when the input signal crosses the threshold limit voltage relative to where in the continuous running internal 10- μ s comparison window the overrange condition occurs. In Figure 34, the output response varies from roughly 2 μ s to approximately 12 μ s when the input exceeds the threshold level. This variance is a result of where in the 10- μ s comparison window the overrange event occurs. If the overrange event occurs late in the 10- μ s comparison window and is large enough to average the entire window measurement up above the threshold level, the alert appears to respond very quickly. If the alert occurs late in the 10- μ s comparison window and is not large enough to average the entire window measurement up above the threshold level, the alert does not appear until the next 10- μ s comparison window completes, assuming the input signal remains above the threshold for the entire duration.

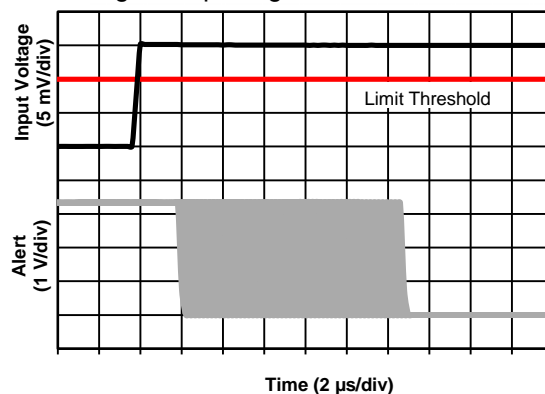


Figure 34. Alert Response

Typical Applications (continued)

8.2.2 Bidirectional Operation

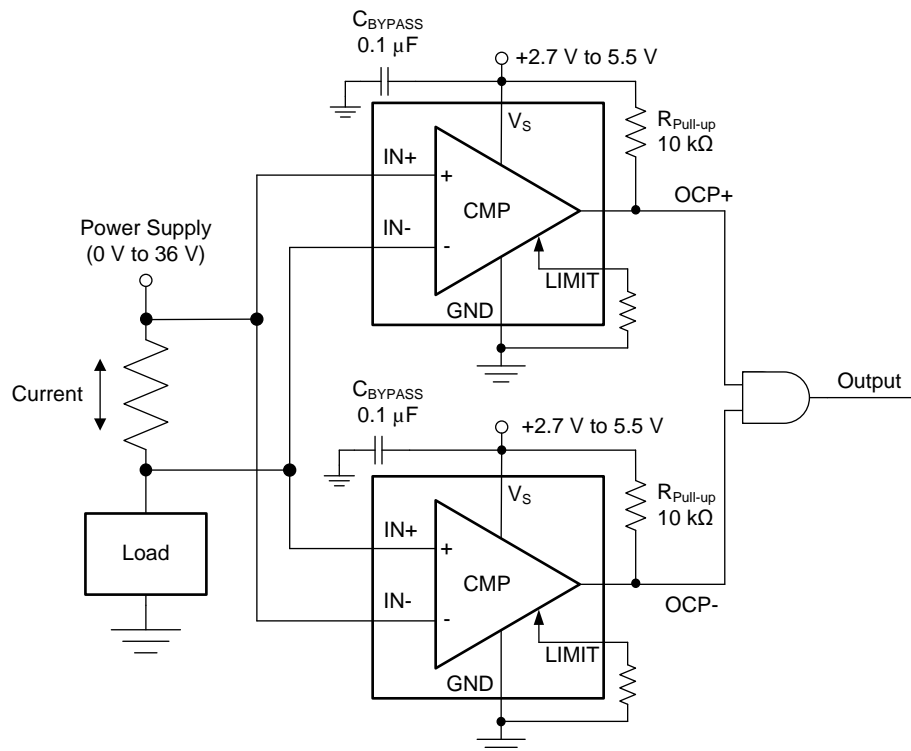


Figure 35. Bidirectional Application

8.2.2.1 Design Requirements

Although the INA300-Q1 device is only able to measure current through a current-sensing resistor flowing in one direction, a second INA300-Q1 device can be used to create a bidirectional monitor.

8.2.2.2 Detailed Design Procedure

With the input terminals of a second INA300-Q1 device reversed across the same current-sensing resistor, the second INA300-Q1 device is now able to detect current flowing in the other direction relative to the first device, as shown in Figure 35. The outputs of each INA300-Q1 device connect to an AND gate to detect if either of the limit threshold levels are exceeded. The output of the AND gate is high if neither overcurrent limit thresholds are exceeded. A low output state of the AND gate indicates that either the positive overcurrent limit or the negative overcurrent limit are surpassed.

Table 8. Bidirectional Overcurrent Output Status

OCP STATUS	OUTPUT
OCP+	0
OCP-	0
No OCP	1

8.2.2.3 Application Curve

Figure 36 illustrates two INA300-Q1 devices being used in a bidirectional configuration and an output control circuit to detect if one of the two alerts is exceeded.

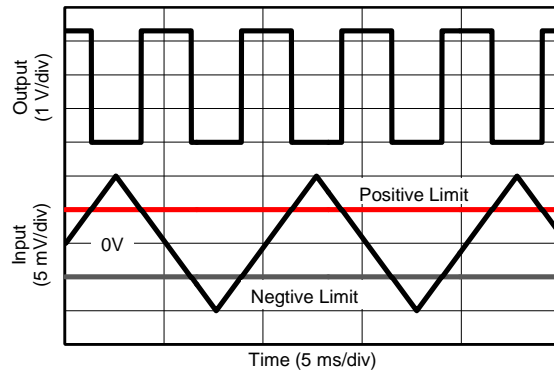


Figure 36. Bidirectional Application Curve

8.2.3 Window Comparator

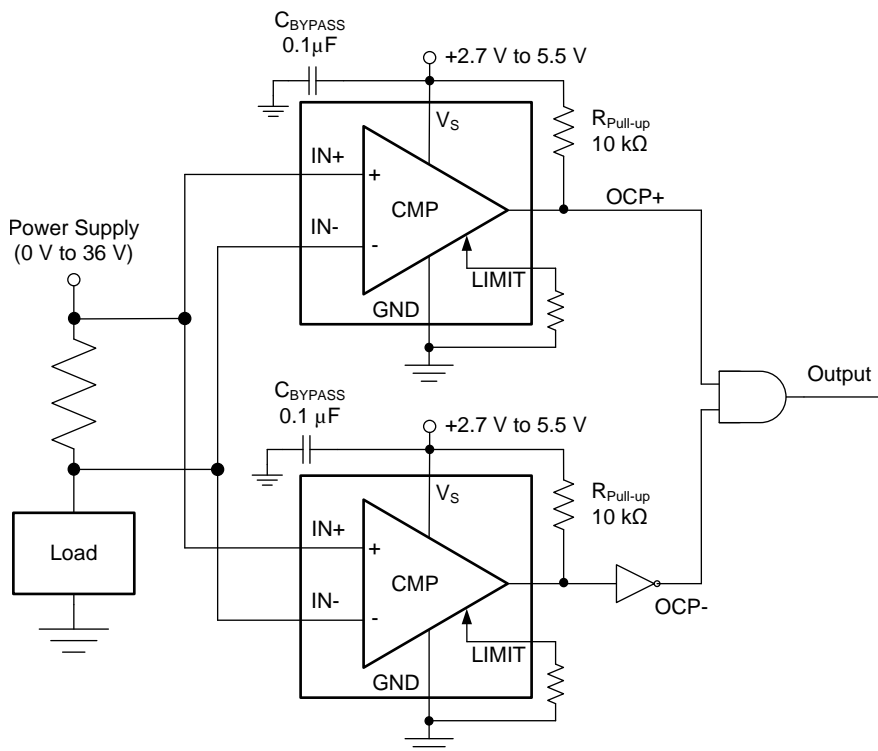


Figure 37. Window Comparator Application

8.2.3.1 Design Requirements

The INA300-Q1 device can be used to create a window comparator function, detecting whether the current being monitored is within a programmed range or has fallen outside of the expected operating region.

8.2.3.2 Detailed Design Procedure

Figure 37 shows how the window comparator function is setup using two INA300-Q1 devices. The input terminals of each INA300-Q1 device are connected to the same current-sensing resistor. The limit threshold for the top device is set to the upper limit of the window range. The bottom device limit threshold is set to the desired lower limit of the range. With a logic inverter placed at the output of the device monitoring the lower limit, the OCP– signal is high when the input signal is above the lower limit threshold. The OCP+ signal is high when the input signal is below the upper limit threshold. A high value at the output (output of the AND gate) indicates that the monitored current is operating within the desired window range.

Table 9. Window Comparator Output Status

INPUT CONDITION	OUTPUT STATUS
Above range	0
Below range	0
In range	1

8.2.3.3 Application Curve

Figure 38 shows the output waveform from the device window comparator application. In Figure 38, the output signal is high when OCP⁻ is low (the input signal is above the lower limit) and when OCP⁺ is high (the input signal is below the upper limit). If the signal rises above the upper limit or drops below the lower limit, the corresponding OCP output changes state, causing the state of the output (following the AND gate) to change to zero to indicate an out-of-range condition.

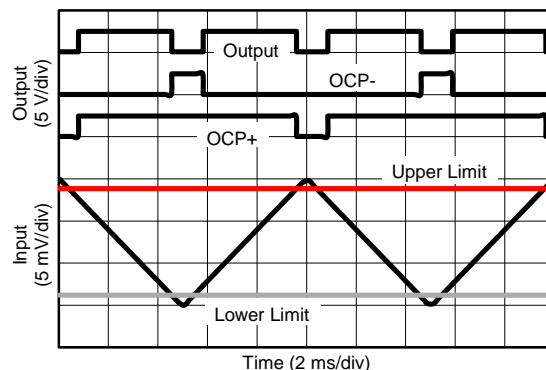


Figure 38. Output Waveform

9 Power Supply Recommendations

The INA300-Q1 device input circuitry can accurately measure signals on common-mode voltages beyond the power-supply voltage, V_S . For example, the voltage applied to the V_S power-supply terminal can be 5 V, whereas the load power-supply voltage being monitored (V_{CM}) can be as high as 36 V. Note that the INA300-Q1 device can withstand the full -0.3 V to $+36$ V range at the input terminals, regardless of whether the device has power applied or not.

Power-supply bypass capacitors are required for stability and must be placed as closely as possible to the supply and ground terminals of the device. A typical value for this supply bypass capacitor is $0.1\ \mu\text{F}$. Applications with noisy or high-impedance power supplies may require additional decoupling capacitors to reject power-supply noise.

10 Layout

10.1 Layout Guidelines

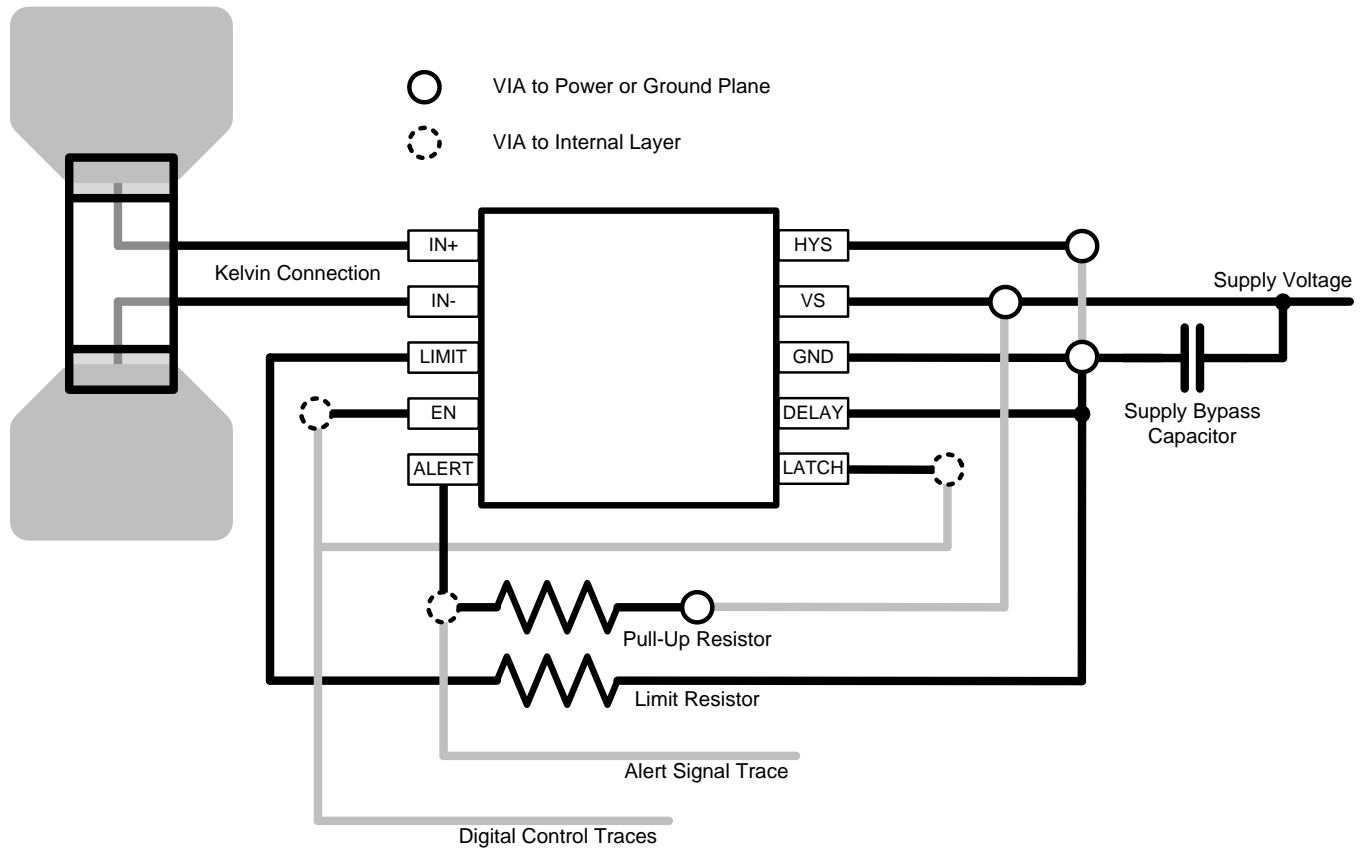
- The power-supply bypass capacitor must be placed as closely as possible to the supply and ground terminals. The recommended value of this bypass capacitor is $0.1\ \mu\text{F}$. Additional decoupling capacitance can be added to compensate for noisy or high-impedance power supplies.
- The connection of R_{LIMIT} to the ground terminal must be made as direct as possible to limit additional capacitance on this node. Routing this connection must be limited to the same plane if possible avoiding vias to internal planes. If the routing cannot be made on the same plane and must pass through vias, ensure that a path is routed from the R_{LIMIT} back to the ground terminal and that the R_{LIMIT} is not connected directly to a ground plane.
- The DELAY terminal must be either connected directly to ground, directly to supply, or left completely floating. Additional external resistors must not be connected to this terminal. If a resistance is required by the application to be placed in series with either the supply or ground connection to the DELAY terminal, this resistance must be limited to $1\ \text{k}\Omega$ so as to not conflict with the internal level detection circuitry.
- The HYS terminal must be either connected directly to ground, directly to supply, or left completely floating. Additional external resistors must not be connected to this terminal. If a resistance is required by the application to be placed in series with either the supply or ground connections to the HYS terminal, this resistance must be limited to $1\ \text{k}\Omega$ so as to not conflict with the internal level detection circuitry.
- The open-drain output pin is recommended to be pulled up to the supply voltage rail through a $10\text{-k}\Omega$ pull-up resistor.

INA300-Q1

ZHCSEX8A – DECEMBER 2015 – REVISED OCTOBER 2016

www.ti.com.cn

10.2 Layout Example



NOTE: Connect the limit resistor directly to the GND terminal.

Figure 39. Recommended Layout for VSSOP Package

11 器件和文档支持

11.1 文档支持

11.1.1 相关文档

相关文档如下：

- 《[INA300EVM 用户指南](#)》（文献编号：SBAU220）。

11.2 接收文档更新通知

如需接收文档更新通知，请访问 www.ti.com.cn 网站上的器件产品文件夹。点击右上角的提醒我 (Alert me) 注册后，即可每周定期收到已更改的产品信息。有关更改的详细信息，请查阅已修订文档中包含的修订历史记录。

11.3 社区资源

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

TI E2E™ Online Community *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

11.4 商标

E2E is a trademark of Texas Instruments.

All other trademarks are the property of their respective owners.

11.5 静电放电警告



ESD 可能会损坏该集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理措施和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

11.6 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

12 机械、封装和可订购信息

以下页中包括机械、封装和可订购信息。这些信息是针对指定器件可提供的最新数据。这些数据会在无通知且不对本文档进行修订的情况下发生改变。欲获得该数据表的浏览器版本，请查阅左侧的导航栏。

重要声明

德州仪器(TI) 及其下属子公司有权根据 JESD46 最新标准, 对所提供的产品和服务进行更正、修改、增强、改进或其它更改, 并有权根据 JESD48 最新标准中止提供任何产品和服务。客户在下订单前应获取最新的相关信息, 并验证这些信息是否完整且是最新的。所有产品的销售都遵循在订单确认时所提供的TI 销售条款与条件。

TI 保证其所销售的组件的性能符合产品销售时 TI 半导体产品销售条件与条款的适用规范。仅在 TI 保证的范围内, 且 TI 认为 有必要时才会使用测试或其它质量控制技术。除非适用法律做出了硬性规定, 否则没有必要对每种组件的所有参数进行测试。

TI 对应用帮助或客户产品设计不承担任何义务。客户应对其使用 TI 组件的产品和应用自行负责。为尽量减小与客户产品和应用相关的风险, 客户应提供充分的设计与操作安全措施。

TI 不对任何 TI 专利权、版权、屏蔽作品权或其它与使用了 TI 组件或服务的组合设备、机器或流程相关的 TI 知识产权中授予 的直接或隐含权限作出任何保证或解释。TI 所发布的与第三方产品或服务有关的信息, 不能构成从 TI 获得使用这些产品或服务 的许可、授权、或认可。使用此类信息可能需要获得第三方的专利权或其它知识产权方面的许可, 或是 TI 的专利权或其它 知识产权方面的许可。

对于 TI 的产品手册或数据表中 TI 信息的重要部分, 仅在没有对内容进行任何篡改且带有相关授权、条件、限制和声明的情况 下才允许进行复制。TI 对此类篡改过的文件不承担任何责任或义务。复制第三方的信息可能需要服从额外的限制条件。

在转售 TI 组件或服务时, 如果对该组件或服务参数的陈述与 TI 标明的参数相比存在差异或虚假成分, 则会失去相关 TI 组件 或服务的所有明示或暗示授权, 且这是不正当的、欺诈性商业行为。TI 对任何此类虚假陈述均不承担任何责任或义务。

客户认可并同意, 尽管任何应用相关信息或支持仍可能由 TI 提供, 但他们将独力负责满足与其产品及其应用中使用的 TI 产品 相关的所有法律、法规和安全相关要求。客户声明并同意, 他们具备制定与实施安全措施所需的全部专业技术和知识, 可预见 故障的危险后果、监测故障及其后果、降低有可能造成人身伤害的故障的发生机率并采取适当的补救措施。客户将全额赔偿因 在此类安全关键应用中使用任何 TI 组件而对 TI 及其代理造成的任何损失。

在某些场合中, 为了推进安全相关应用有可能对 TI 组件进行特别的促销。TI 的目标是利用此类组件帮助客户设计和创立其特 有的可满足适用的功能安全性标准和要求的终端产品解决方案。尽管如此, 此类组件仍然服从这些条款。

TI 组件未获得用于 FDA Class III (或类似的生命攸关医疗设备) 的授权许可, 除非各方授权官员已经达成了专门管控此类使 用的特别协议。

只有那些 TI 特别注明属于军用等级或“增强型塑料”的 TI 组件才是设计或专门用于军事/航空应用或环境的。购买者认可并同 意, 对并非指定面向军事或航空航天用途的 TI 组件进行军事或航空航天方面的应用, 其风险由客户单独承担, 并且由客户独 力负责满足与此类使用相关的所有法律和法规要求。

TI 已明确指定符合 ISO/TS16949 要求的产品, 这些产品主要用于汽车。在任何情况下, 因使用非指定产品而无法达到 ISO/TS16949 要求, TI 不承担任何责任。

	产品		应用
数字音频	www.ti.com.cn/audio	通信与电信	www.ti.com.cn/telecom
放大器和线性器件	www.ti.com.cn/amplifiers	计算机及周边	www.ti.com.cn/computer
数据转换器	www.ti.com.cn/dataconverters	消费电子	www.ti.com.cn/consumer-apps
DLP® 产品	www.dlp.com	能源	www.ti.com.cn/energy
DSP - 数字信号处理器	www.ti.com.cn/dsp	工业应用	www.ti.com.cn/industrial
时钟和计时器	www.ti.com.cn/clockandtimers	医疗电子	www.ti.com.cn/medical
接口	www.ti.com.cn/interface	安防应用	www.ti.com.cn/security
逻辑	www.ti.com.cn/logic	汽车电子	www.ti.com.cn/automotive
电源管理	www.ti.com.cn/power	视频和影像	www.ti.com.cn/video
微控制器 (MCU)	www.ti.com.cn/microcontrollers		
RFID 系统	www.ti.com.cn/rfidsys		
OMAP应用处理器	www.ti.com.cn/omap		
无线连通性	www.ti.com.cn/wirelessconnectivity	德州仪器在线技术支持社区	www.deyisupport.com

邮寄地址: 上海市浦东新区世纪大道1568号, 中建大厦32楼邮政编码: 200122
Copyright © 2016, 德州仪器半导体技术(上海)有限公司

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
INA300AQDGSRQ1	ACTIVE	VSSOP	DGS	10	2500	RoHS & Green	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	300Q	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
INA300AQDGSRQ1	VSSOP	DGS	10	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
INA300AQDGSRQ1	VSSOP	DGS	10	2500	366.0	364.0	50.0



4221984/A 05/2015

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-187, variation BA.

EXAMPLE BOARD LAYOUT

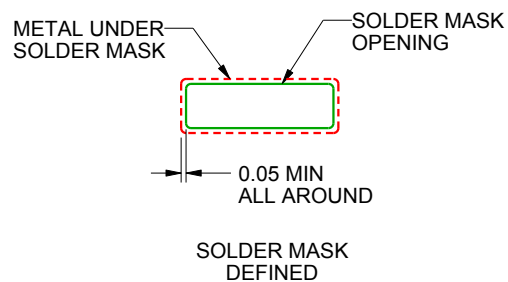
DGS0010A

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
SCALE:10X



SOLDER MASK DETAILS
NOT TO SCALE

4221984/A 05/2015

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DGS0010A

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:10X

4221984/A 05/2015

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

重要声明和免责声明

TI 均以“原样”提供技术性 & 可靠性数据（包括数据表）、设计资源（包括参考设计）、应用或其他设计建议、网络工具、安全信息和其他资源，不保证其中不含任何瑕疵，且不做任何明示或暗示的担保，包括但不限于对适销性、适合某特定用途或不侵犯任何第三方知识产权的暗示担保。

所述资源可供专业开发人员应用 TI 产品进行设计使用。您将对以下行为独自承担全部责任：(1) 针对您的应用选择合适的 TI 产品；(2) 设计、验证并测试您的应用；(3) 确保您的应用满足相应标准以及任何其他安全、安保或其他要求。所述资源如有变更，恕不另行通知。TI 对您使用所述资源的授权仅限于开发资源所涉及 TI 产品的相关应用。除此之外不得复制或展示所述资源，也不提供其它 TI 或任何第三方的知识产权授权许可。如因使用所述资源而产生任何索赔、赔偿、成本、损失及债务等，TI 对此概不负责，并且您须赔偿由此对 TI 及其代表造成的损害。

TI 所提供产品均受 TI 的销售条款 (<http://www.ti.com.cn/zh-cn/legal/termsofsale.html>) 以及 [ti.com.cn](http://www.ti.com.cn) 上或随附 TI 产品提供的其他可适用条款的约束。TI 提供所述资源并不扩展或以其他方式更改 TI 针对 TI 产品所发布的可适用的担保范围或担保免责声明。

邮寄地址：上海市浦东新区世纪大道 1568 号中建大厦 32 楼，邮政编码：200122
Copyright © 2020 德州仪器半导体技术（上海）有限公司